3.3V Dual LVTTL/LVCMOS to Differential LVPECL Translator

Description

The MC100LVELT22 is a dual LVTTL/LVCMOS to differential LVPECL translator. Because LVPECL (Low Voltage Positive ECL) levels are used, only +3.3 V and ground are required. The small outline 8-lead package and the low skew, dual gate design of the LVELT22 makes it ideal for applications which require the translation of a clock and a data signal.

Features

- 350 ps Typical Propagation Delay
- <100 ps Output-to-Output Skew
- Flow Through Pinouts
- The 100 Series Contains Temperature Compensation
- LVPECL Operating Range: V_{CC} = 3.0 V to 3.8 V with GND = 0 V
- When Unused TTL Input is left Open, Q Output will Default High
- Pb-Free Packages are Available



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MARKING DIAGRAMS*



SOIC-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R





DFN8 MN SUFFIX CASE 506AA



A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

 \overline{M} = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)
*For additional marking information, refer to
Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

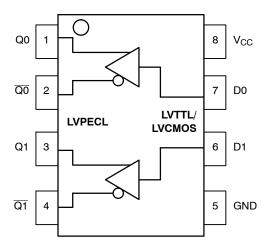


Table 1. PIN DESCRIPTION

PIN	FUNCTION
Qn, Qn D0, D1 V _{CC} GND	LVPECL Differential Outputs LVTTL/LVCMOS Inputs Positive Supply Ground
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

ΕP

Table 2. ATTRIBUTES

Characte	Value			
Internal Input Pulldown Resistor	N/A			
Internal Input Pullup Resistor	N/A			
ESD Protection	Human Body Model Machine Model	> 4 kV > 200 V		
Moisture Sensitivity, Indefinite Tim	ne Out of Drypack (Note 1)	Level 1		
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
Transistor Count	164			
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test				

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		7	V
VI	Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	7	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SO-8 SO-8	190 130	°C/W
θЈС	Thermal Resistance (Junction-to-Case)	std bd	SO-8	41 to 44 ± 5%	°C/W
θJA	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	std bd	TSSOP-8	41 to 44 ± 5%	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 4. LVPECL DC CHARACTERISTICS V_{CC} = 3.3 V; GND = 0.0 V (Note 3)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	Power Supply Current			28			28			29	mA
V _{OH}	Output HIGH Voltage (Note 4)	2275		2420	2275		2420	2275		2420	mV
V _{OL}	Output LOW Voltage (Note 4)	1490		1680	1490		1680	1490		1680	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary ± 0.15 V. 4. Outputs are terminated through a 50 ohm resistor to V_{CC} –2 volts.

Table 5. LVTTL/LVCMOS INPUT DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (Note 5)

Symbol	Characteristic	Min	Тур	Max	Unit	Condition
I _{IH}	Input HIGH Current			20	μΑ	V _{IN} = 2.7 V
I _{IHH}	Input HIGH Current			100	μΑ	V _{IN} = V _{CC}
Iլ∟	Input LOW Current			-0.2	mA	V _{IN} = 0.5 V
V _{IK}				-1.2	V	I _{IN} = -18 mA
V _{IH}	Input HIGH Voltage	2.0			V	
V _{IL}	Input LOW Voltage			0.8	V	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. V_{CC} can vary ±0.15 V.

Table 6. AC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; GND = 0.0 V (Note 6)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency					350					MHz
^t PLH	Propagation Delay (Note 7)	200	350	600	200	350	600	200	350	600	ps
t skew	Skew Output-to-Output Part-to-Part		30	100 400		30	100 400		30	100 400	ps
tJITTER	Random Clock Jitter (RMS)					1.6					ps
t /t r f	Output Rise/Fall Time (20-80%)	200		550	200		500	200		500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. V_{CC} can vary ± 0.15 V.
- 7. Specifications for standard TTL input signal.

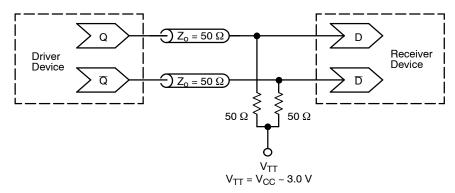


Figure 1. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVELT22D	SOIC-8	98 Units / Rail
MC100LVELT22DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100LVELT22DR2	SOIC-8	2500 / Tape & Reel
MC100LVELT22DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100LVELT22DT	TSSOP-8	100 Units / Rail
MC100LVELT22DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100LVELT22DTR2	TSSOP-8	2500 / Tape & Reel
MC100LVELT22DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100LVELT22MNR4	DFN8	1000 / Tape & Reel
MC100LVELT22MNRG	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

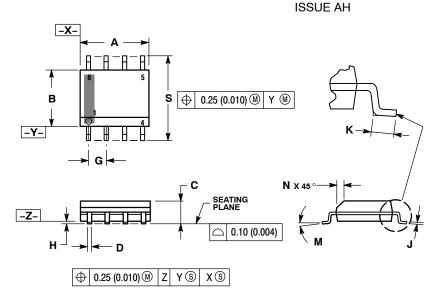
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07

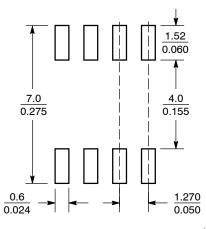


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.
 751-01 THRU 751-06 ARE OBSOLETE. NEW
 STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*



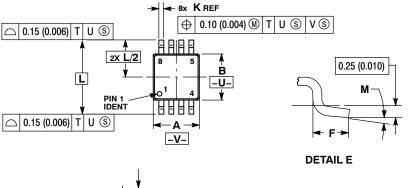
 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**

DETAIL E



<u>0.10 (0.004)</u> _T_ SEATING PLANE

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
 PER SIDE.

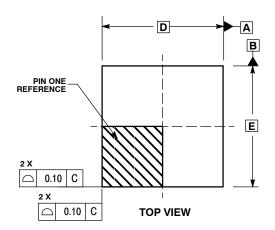
 5. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.

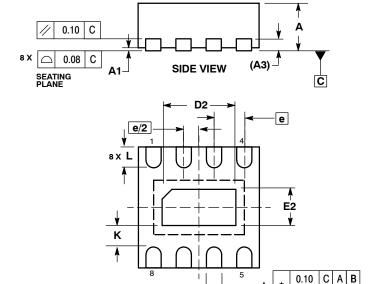
 6. DIMENSION A AND B ARE TO BE DETERMINED
 AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026	BSC
K	0.25	0.40	0.010	0.016
L	4.90	BSC	0.193	
M	0°	6 °	0°	6°

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D





NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
- ASME Y14.3M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.

 4. COPLANARITY APPLIES TO THE EXPOSED DAD A COMPTL AS THE TERMINAL.
- PAD AS WELL AS THE TERMINALS.

	MILLIN	MILLIMETERS				
DIM	MIN	MAX				
Α	0.80	1.00				
A1	0.00	0.05				
А3	0.20	REF				
b	0.20	0.30				
D	2.00	BSC				
D2	1.10	1.30				
Е	2.00	BSC				
E2	0.70	0.90				
е	0.50 BSC					
K	0.20					
L	0.25	0.35				

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MAX3371ELT+T MAX3008EUP+T NLVPCA9306AMUTCG NLSX3013BFCT1G MAX9378EUA+T NLV7WBD3125USG
NLV14504BDTG NLSX3012DMR2G NLSX5012DR2G MAX3391EEUD+T MAX3379EETD+ PI4ULS3V4857GEAEX
MAX3391EEBC+T MAX14842ATE+T 74AVCH1T45FZ4-7 CLVC16T245MDGGREP HEF4104BT TC74LCX16245(EL,F)
MC10H124FNG CAVCB164245MDGGREP 7WBD383USG NVT2001GM,115 CLVC8T245MRHLTEP 74LVC1G175GS,132
FXLA104UM12X